



Material Content Data Sheet



Sales Product Name		BSV236SP H6327		Issued		25. January 2018		
MA#		MA001216314						
Package		PG-SOT363-6-6		Weight*		6.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.06		606	
	noble metal	gold	7440-57-5	0.016	0.24		2352	
	inorganic material	silicon	7440-21-3	0.177	2.67	2.97	26652	29610
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		495	
	non noble metal	chromium	7440-47-3	0.010	0.15		1484	
	non noble metal	copper	7440-50-8	3.275	49.25	49.46	492645	494723
wire	non noble metal	copper	7440-50-8	0.012	0.18	0.18	1770	1770
encapsulation	organic material	carbon black	1333-86-4	0.029	0.43		4303	
	plastics	epoxy resin	-	0.615	9.25		92520	
	inorganic material	silicondioxide	60676-86-0	2.217	33.35	43.03	333504	430327
leadfinish	non noble metal	tin	7440-31-5	0.213	3.21	3.21	32071	32071
plating	noble metal	silver	7440-22-4	0.076	1.15	1.15	11499	11499
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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